



Product Summary

BV _{DSS}	Max R _{DS(on)}	Max I _D T _A = +25°C (Note 6)
100V	230mΩ @ V _{GS} = 10V	1.9A
100 v	$300m\Omega @ V_{GS} = 4.5V$	1.68A

Description and Applications

This MOSFET utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes it ideal for high-efficiency, low voltage, power management applications.

- DC DC Converters
- Power Management Functions
- Disconnect Switches
- Motor Control

100V N-CHANNEL ENHANCEMENT MODE MOSFET

Features and Benefits

- Low On-Resistance
- Fast Switching Speed
- Low Threshold
- Low Gate Drive
- SOT26 Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

Case: SOT26

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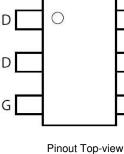
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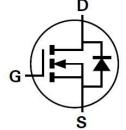
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.015 grams (Approximate)



SOT26

Top View





Device Symbol

Ordering Information (Note 4)

Part Number	Reel Size (inch)	Tape Width (mm)	Quantity Per Reel
ZXMN10B08E6TA	7	8	3,000
ZXMN10B08E6TC	13	8	10,000

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com.

Marking Information

marking init	ormatic	n										
			S	OT26								
					-							
Date Code Key			1(●)B8 ≥		YM = Da Y or	Product Typ te Code Ma Year (ex: C Month (ex	arking C = 2015)				
Year	2015		2016	2017		2018	2019		2020	2021		2022
Code	С		D	E		F	G		Н			J
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D
ZXMN10B08E	E6					1 of 7						March 2015

Datasheet Number: DS33570 Rev. 3 – 2

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Maximum Ratings (@T_A = +25 °C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	100	V
Gate-Source Voltage			V _{GSS}	±20	V
		(Note 6)		1.9	
Continuous Drain Current	$V_{GS} = 10V$	$T_A = +70^{\circ}C$ (Note 6)	ID	1.5	А
		(Note 5)		1.6	
Pulsed Drain Current		(Note 7)	I _{DM}	9	А
Continuous Source Current (Body Diode)		(Note 6)	Is	2.5	А
Pulsed Source Current (Body Diode) (Note		(Note 7)	I _{SM}	9	А

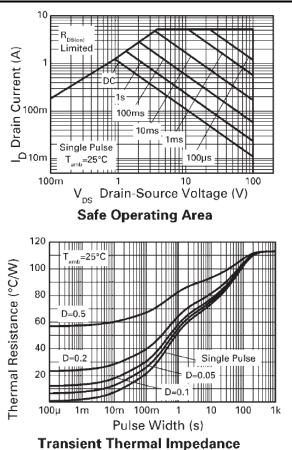
Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

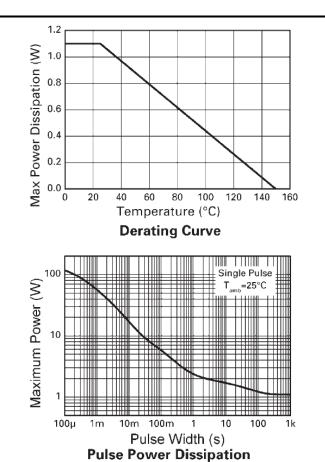
Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 5)	D-	1.1	W
Linear Derating Factor	(INDLE 5)	PD	8.8	mW/°C
Power Dissipation	(Nata C)	D	1.7	W
Linear Derating Factor	(Note 6)	PD	13.6	mW/°C
Thermal Desistance Junction to Ambient	(Note 5)	5	113	0 0 MU
Thermal Resistance, Junction to Ambient	(Note 6)	R _{θJA}	73	°C/W
Operating and Storage Temperature Range		TJ, T _{STG}	-55 to +150	°C

Notes: 5. For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

 6. For a device surface mounted on FR4 PCB measured at t ≤ 5 secs.
 7. Repetitive rating 25mm x 25mm FR4 PCB, D = 0.02, pulse width 300µs - pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.

Thermal Characteristics







Electrical Characteristics (@T_A = +25 °C, unless otherwise specified.)

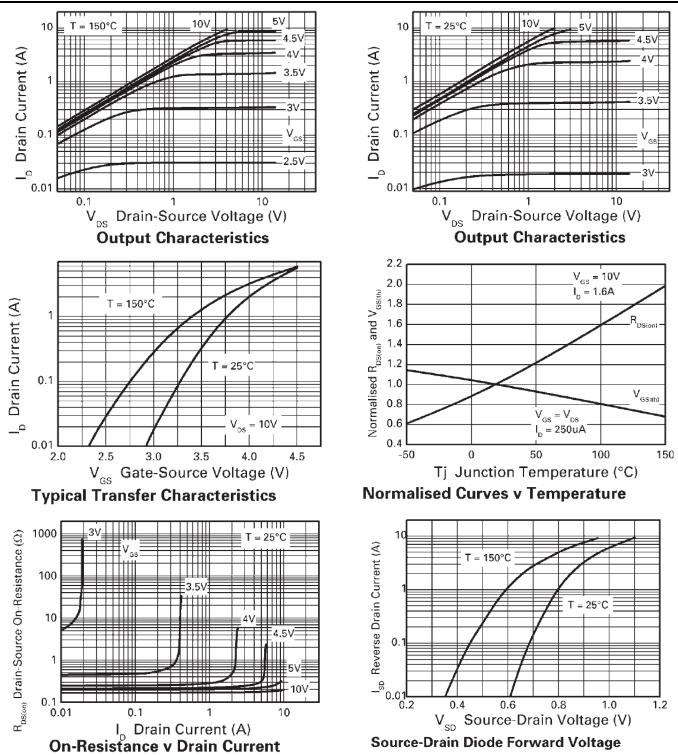
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS				•		÷	
Drain-Source Breakdown Voltage	BV _{DSS}	100		_	V	$I_D = 250 \mu A, V_{GS} = 0 V$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	0.5	μΑ	$V_{DS} = 100V, V_{GS} = 0V$	
Gate-Source Leakage	IGSS			100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS							
Gate Threshold Voltage	V _{GS(th)}	1.0		3.0	V	$I_D = 250 \mu A$, $V_{DS} = V_{GS}$	
				0.23		$V_{GS} = 10V, I_D = 1.6A$	
Static Drain-Source On-Resistance (Note 8)	R _{DS(ON)}	_		0.30	Ω	$V_{GS} = 4.5V, I_D = 1.4A$	
				0.50		V _{GS} = 4.3V, I _D = 1.1A	
Forward Transconductance (Notes 8 & 10)	g fs	_	4.8	_	S	V _{DS} = 15V, I _D = 1.6A	
Diode Forward Voltage (Note 8)	V _{SD}		0.85	0.95	V	$T_J = +25 \text{°C}, I_S = 2.0 \text{A}, V_{GS} = 0 \text{V}$	
DYNAMIC CHARACTERISTICS (Note 10)				•		•	
Input Capacitance	C _{iss}	_	497	_	pF		
Output Capacitance	C _{oss}	_	29	_	pF	V _{DS} = 50V, V _{GS} = 0V f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	_	18	_	pF		
Gate Charge (Note 9)	Qg	_	5.0	_	nC	$V_{DS} = 50V$, $V_{GS} = 5V$, $I_D = 1.6A$	
Total Gate Charge (Note 9)	Qg	_	9.2	_	nC		
Gate-Source Charge (Note 9)	Q _{gs}	_	1.7	_	nC	$V_{DS} = 50V, V_{GS} = 10V,$ $-I_{D} = 1.6A$	
Gate-Drain Charge (Note 9)	Q _{gd}		2.5	_	nC	$I_D = 1.6A$	
Turn-On Delay Time (Note 9)	t _{d(on)}	_	2.9	_	ns		
Turn-On Rise Time (Note 9)	tr		2.1	_	ns	$V_{DD} = 50V, I_D = 1.0A,$	
Turn-Off Delay Time (Note 9)	t _{d(off)}	_	12.1	_	ns	$R_G \cong 6.0\Omega, V_{GS} = 10V$	
Turn-Off Fall Time (Note 9)	tf	_	5.0	_	ns	7	
Reverse Recovery Time	t _{rr}	_	32	_	ns	T,J = +25 ℃, I _F = 1.7A,	
Reverse Recovery Charge	Q _{rr}		40	_	nC	$di/dt = 100 A/\mu s$	

Notes:

8. Measured under pulsed conditions. Width \leq 300µs. Duty cycle \leq 2%. 9. Switching characteristics are independent of operating junction temperature. 10. For design aid only, not subject to production testing.

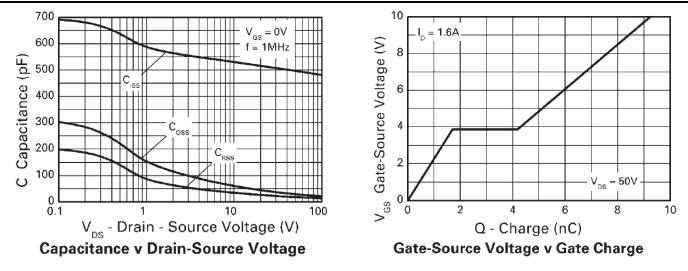


Typical Characteristics

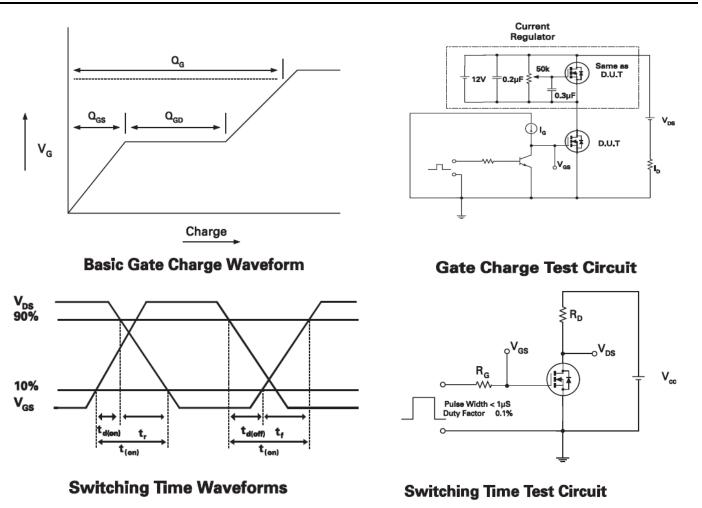




Typical Characteristics (continued)



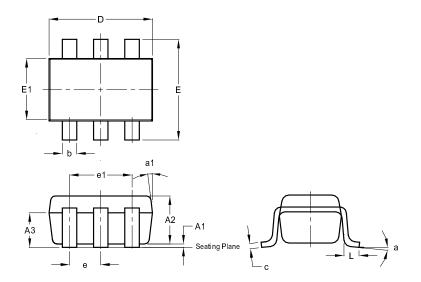
Test Circuits





Package Outline Dimensions

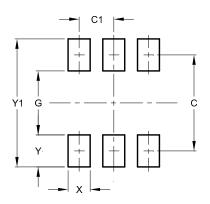
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



	SOT26							
Dim	Min	Max	Тур					
A1	0.013	0.10	0.05					
A2	1.00	1.30	1.10					
A3	0.70	0.80	0.75					
b	0.35	0.50	0.38					
С	0.10	0.20	0.15					
D	2.90	3.10	3.00					
е	-	-	0.95					
e1	-	-	1.90					
Е	2.70	3.00	2.80					
E1	1.50	1.70	1.60					
L	0.35	0.55	0.40					
а	-	-	8°					
a1	-	-	7°					
All	Dimen	sions	in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	2.40
C1	0.95
G	1.60
Х	0.55
Y	0.80
Y1	3.20



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